

In re application of : Confirmation No. 5528

Etsuko NAKAMURA et al. : Attorney Docket No. 2003_1698A

Serial No. 10/721,164 : Group Art Unit 1752

Filed November 26, 2003 : Examiner Amanda C. Walke

LOWER LAYER MATERIAL FOR WIRING, EMBEDDED MATERIAL, AND WIRING FORMATION METHOD Mail Stop: AMENDMENT

AMENDMENT

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

In response to the Official Action dated August 10, 2006, please amend the present application as follows:

THE COMMISSIONER IS AUTHORIZED TO CHARGE ANY DEFICIENCY IN THE FEES FOR THIS PAPER TO DEPOSIT ACCOUNT NO. 23-0975